

POLISHING APPARATUS AND POLISHING METHOD

ABSTRACT

It is an object of the present invention to improve the accuracy of polishing end point detection in a polishing scheme of holding a top ring at an end portion of a swing arm. A polishing pad is held using a polishing table. The polishing table is driven to rotate using a first electric motor. The top ring for holding a semiconductor wafer and pressing the top ring against a polishing pad is driven to rotate by a top ring motor. The top ring is held by the swing arm. The swing arm is made to swing around a swing center on the swing arm by a swing shaft motor. A first output is generated by detecting a current value of the swing shaft motor. While polishing the semiconductor wafer by causing the semiconductor wafer to swing around the swing center on the swing arm, a change of a frictional force between the polishing pad and the semiconductor wafer is detected by increasing a change amount of the first output.

Representative drawing: Fig. 16